EverTherm™

Technical Data Sheet

EVSF100

Product Description

CR Technology offers a wide variety of thermally conductive pads also known as gap fillers. These materials are available in both silicone and non-silicone formulations. EVERTHERM pads offer an endless range of thermal conductivity, softness and thickness options to easily solve any heat related issue. EVERTHERM pads are naturally tacky and can be cut to any size or shape for easy installation. EVERTHERM pads are designed and engineered to achieve the highest level of thermal management to protect today's most advanced electronics.

Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Color		Visual
Thickness	1.0mm	ASTM D374
Thermal Conductivity		ASTM D5470
Specific Gravity	2.1g/cc	ASTM D792
Hardness (Shore OO)		ASTM D2240
Elongation	50%	ASTM D412
Tensile Strength		ASTM D412
Electrical Strength		
UL Flammability Rating	UL94 V-0	
Volume Resistivity		ASTM D257
Operating Temperature		——
Thermal Resistance(1mm,@40psi)	0.9℃*in2/W	ASTM D5470
Compression Ratio(1mm,@40psi)		——
Dielectric Constant MHz	5.5	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN14372
Standard Sheet Size *(Note: Other sheet sizes may be available upon request.)*	200mm x 300mm	

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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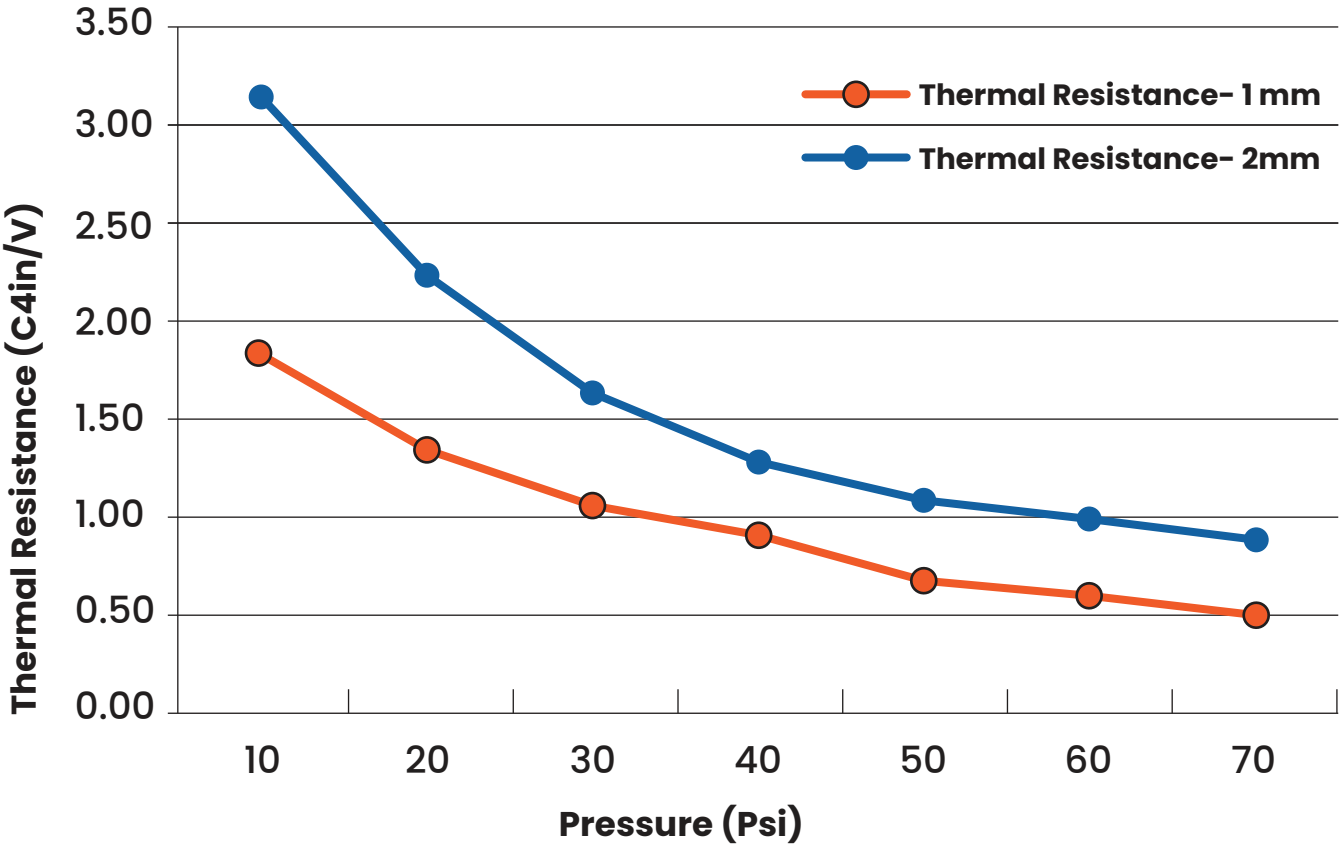
Applications

- Semiconductor heat sink
- Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- LED lighting equipment
- Electronic components like:
  LEDs, CPUs, MOS • Mobiles, Laptops, Tablets

Thermal Resistance VS Pressure



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